

ABSTRACT OF THE DISCLOSURE

A window via capacitor comprises a stacked multilayer configuration of at least one bottom layer, a plurality of first and second layers, a transition layer and a cover layer. Each first and second layer is preferably characterized by a sheet of dielectric material with a respective first or second electrode plate provided thereon. Adjacent first and second electrode plates form opposing active capacitor plates in the multilayer configuration. Portions of each first and second electrode plate extend to and are exposed on selected periphery side portions. Electrode portions of each transition layer are aligned in respective similar locations to the first and second electrode plates such that peripheral terminations can connect selected electrode portions of a first polarity together and selected portions of the opposing polarity together. Solder balls may also be applied to window vias to yield a capacitor compatible with BGA mounting technology.